



15th International Conference on Bond Graph Modeling and Simulation

JULY 1-3, 2024 • HILTON GARDEN INN • SAN DIEGO, CALIFORNIA

ANNOUNCEMENT AND CALL FOR PAPERS

The Society for Modeling and Simulation International (SCS)
The American Institute for Aeronautics and Astronautics (AIAA)

The 2024 INTERNATIONAL CONFERENCE ON BOND GRAPH MODELING AND SIMULATION
July 1-3, 2024 • Hilton Garden Inn • 4200 Taylor Street, San Diego, CA 92110 USA

The 2024 International Conference on Bond Graph Modeling and Simulation brings together research paper presentations, panel sessions, tutorials, workshops, seminars, industrial applications, and software demonstrations that use Bond Graph modeling methods. There will be also featured plenary speakers and some special invited presentations.

This conference will focus on Bond Graph modeling techniques for dynamic systems. Theoretical principles for electrical, mechanical, hydraulic, pneumatic, and control system applications will be presented. Leading industrial users of the method in automotive, aircraft, fluid power, kinematics, multibody systems, and social and biological systems have been invited. Research papers are welcome in the following categories of presentation.

SESSIONS

. Tutorials	Mechanical Systems and Robotics
. Panel Discussions	Electrical and Power Systems
. Software and Tools	Control Systems
. Bond Graph Theory	Thermal and Chemical Systems
. Advanced Bond Graph Methodology	Biomechanics and Prosthetics
. Bond Graphs and Block Diagrams	Ecological Systems
. Computer Graphics and	Biological and Medical Systems
Bond Graph Modeling	Social and Economic Systems
. Qualitative Modeling	Industrial Applications
. Mechatronics Systems	Large, Nonlinear Models

DEADLINES

- February 1, 2024 Short Abstracts due
 - February 15, 2024 Abstract Acceptance Author Notifications:
 - March 15, 2024 Full Papers for Peer Review Due:
 - April 15, 2024 Paper Acceptance Notifications
 - May 1, 2024 Camera Ready Paper Submission
- Where to submit: For abstracts and papers, go to <https://www.softconf.com/sim/ICBGM24/> or via email directly to the one of the chairs.

Abstracts and full papers can be submitted via email alternatively to the General Chair or the Program Chair. In addition to regular papers about 12 pages (double spaced), the program committee may accept additional papers, either as short papers (about 6 pages double-spaced), or proposals for tutorials. Please add a cover letter stating your name, affiliation, mail address, telephone number, FAX number, and e-mail address. The two Chairs will review the short abstracts for general suitability to the conference. Members of the International Program Committee will review each full paper.

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